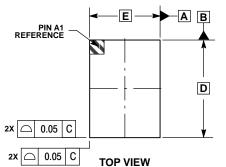
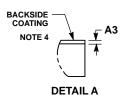


WLCSP15, 2.15x1.55 CASE 567HY **ISSUE B**

DATE 30 APR 2015



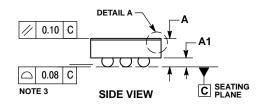


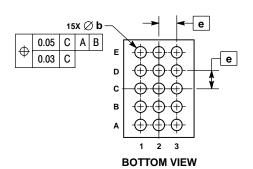
NOTES:

- NOTES:

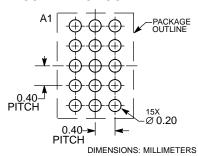
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
 4. BACKSIDE COATING IS OPTIONAL.

| | MILLIMETERS | | |
|-----|-------------|------|--|
| DIM | MIN | MAX | |
| Α | | 0.65 | |
| A1 | 0.16 | 0.26 | |
| A3 | 0.025 REF | | |
| b | 0.21 | 0.31 | |
| D | 2.15 BSC | | |
| E | 1.55 BSC | | |
| е | 0.40 BSC | | |





RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| 98AON76308 | 3F |

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| ISSUE | REVISION | DATE |
|-------|--|-------------|
| 0 | RELEASED FOR PRODUCTION. REQ. BY I. CAMBALIZA. | 19 JUL 2013 |
| Α | CHANGED DIMENSION A TO 0.625. REQ. BY K. SAITO. | 10 APR 2014 |
| В | ADDED BACKSIDE COATING OPTION INFORMATION. REQ. BY K. OKADA. | 30 APR 2015 |
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